Special Issue

Machine Learning for Thermal Sensing and Analysis

Message from the Guest Editors

Temperature is one of the most fundamental parameters characterizing a physical system. The developments in thermal sensing over the past few decades have generated both direct and indirect thermal sensors with various performances and costs. Temperature sensing data can be 1D temporal data or 2D images for thermography. With the increasing sensing data and computing power, a new trend is to go beyond the quantification of the sensing events and integrate with machine learning algorithms. Such data-driven techniques have promising potential for improved automation and intelligent analysis in both industry and academia. This Special Issue aims to provide a platform to communicate and discuss the development of deep learning and AI techniques for analyzing thermal sensors and thermal imaging. We invite research papers, reviews, and shorter communications that focus on the use of deep learning models for innovative applications related to thermal sensing.

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